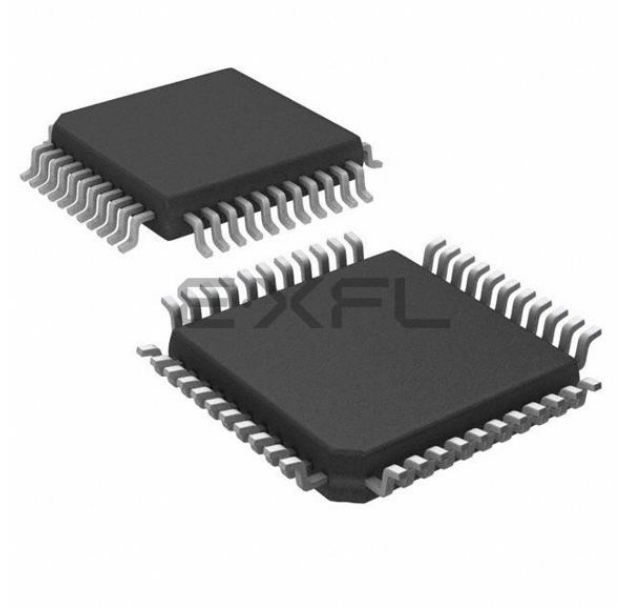

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Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	33
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	368 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-QFP
Supplier Device Package	44-MQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f877t-20i-pq

1.0 DEVICE OVERVIEW

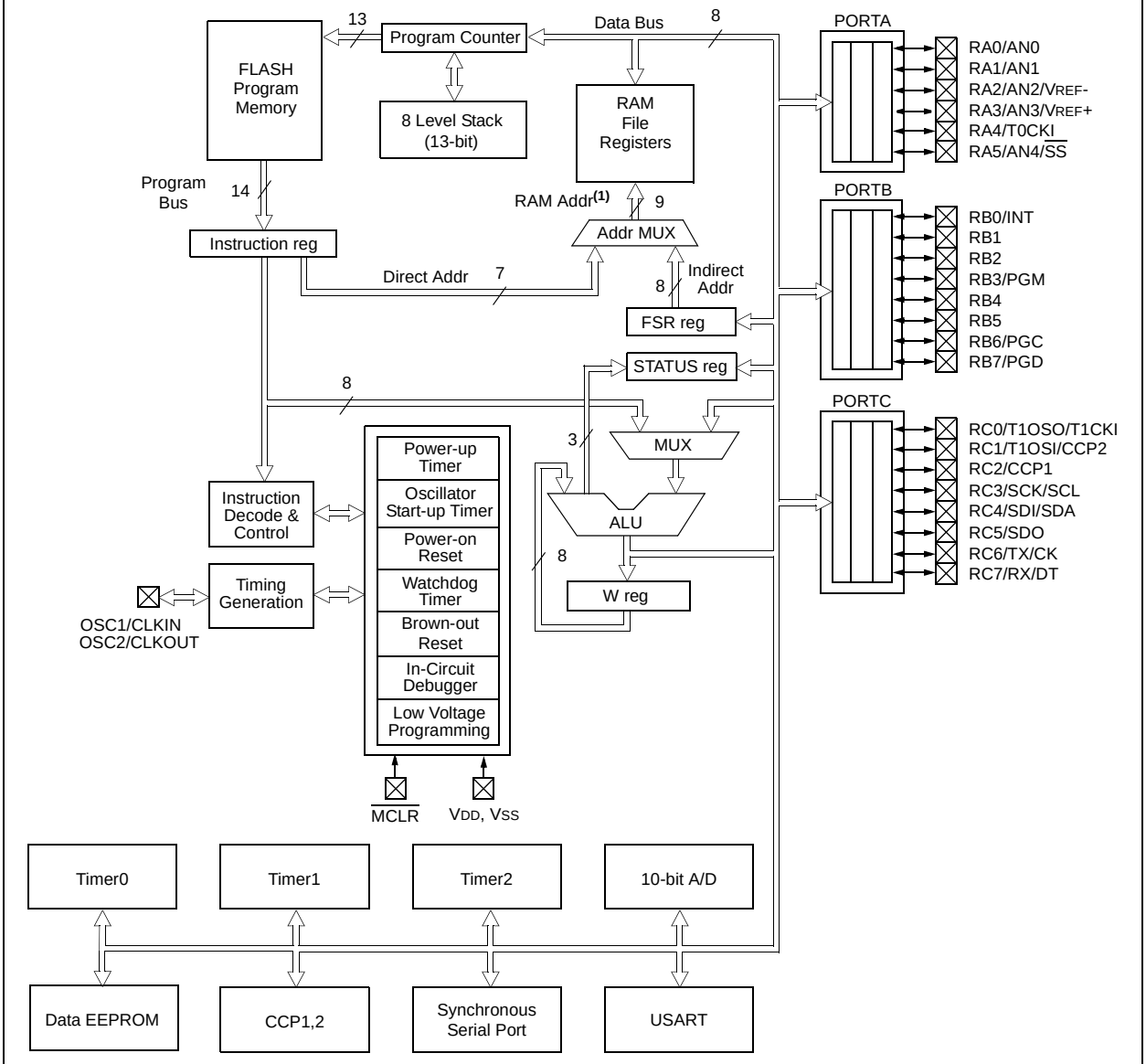
This document contains device specific information. Additional information may be found in the PIC® MCU Mid-Range Reference Manual (DS33023), which may be obtained from your local Microchip Sales Representative or downloaded from the Microchip website. The Reference Manual should be considered a complementary document to this data sheet, and is highly recommended reading for a better understanding of the device architecture and operation of the peripheral modules.

There are four devices (PIC16F873, PIC16F874, PIC16F876 and PIC16F877) covered by this data sheet. The PIC16F876/873 devices come in 28-pin packages and the PIC16F877/874 devices come in 40-pin packages. The Parallel Slave Port is not implemented on the 28-pin devices.

The following device block diagrams are sorted by pin number; 28-pin for Figure 1-1 and 40-pin for Figure 1-2. The 28-pin and 40-pin pinouts are listed in Table 1-1 and Table 1-2, respectively.

FIGURE 1-1: PIC16F873 AND PIC16F876 BLOCK DIAGRAM

Device	Program FLASH	Data Memory	Data EEPROM
PIC16F873	4K	192 Bytes	128 Bytes
PIC16F876	8K	368 Bytes	256 Bytes



Note 1: Higher order bits are from the STATUS register.

TABLE 1-2: PIC16F874 AND PIC16F877 PINOUT DESCRIPTION (CONTINUED)

Pin Name	DIP Pin#	PLCC Pin#	QFP Pin#	I/O/P Type	Buffer Type	Description
						PORTC is a bi-directional I/O port.
RC0/T1OSO/T1CKI	15	16	32	I/O	ST	RC0 can also be the Timer1 oscillator output or a Timer1 clock input.
RC1/T1OSI/CCP2	16	18	35	I/O	ST	RC1 can also be the Timer1 oscillator input or Capture2 input/Compare2 output/PWM2 output.
RC2/CCP1	17	19	36	I/O	ST	RC2 can also be the Capture1 input/Compare1 output/PWM1 output.
RC3/SCK/SCL	18	20	37	I/O	ST	RC3 can also be the synchronous serial clock input/output for both SPI and I^2C modes.
RC4/SDI/SDA	23	25	42	I/O	ST	RC4 can also be the SPI Data In (SPI mode) or data I/O (I^2C mode).
RC5/SDO	24	26	43	I/O	ST	RC5 can also be the SPI Data Out (SPI mode).
RC6/TX/CK	25	27	44	I/O	ST	RC6 can also be the USART Asynchronous Transmit or Synchronous Clock.
RC7/RX/DT	26	29	1	I/O	ST	RC7 can also be the USART Asynchronous Receive or Synchronous Data.
						PORTD is a bi-directional I/O port or parallel slave port when interfacing to a microprocessor bus.
RD0/PSP0	19	21	38	I/O	ST/TTL(3)	
RD1/PSP1	20	22	39	I/O	ST/TTL(3)	
RD2/PSP2	21	23	40	I/O	ST/TTL(3)	
RD3/PSP3	22	24	41	I/O	ST/TTL(3)	
RD4/PSP4	27	30	2	I/O	ST/TTL(3)	
RD5/PSP5	28	31	3	I/O	ST/TTL(3)	
RD6/PSP6	29	32	4	I/O	ST/TTL(3)	
RD7/PSP7	30	33	5	I/O	ST/TTL(3)	
						PORTE is a bi-directional I/O port.
RE0/$\overline{RD}$/AN5	8	9	25	I/O	ST/TTL(3)	RE0 can also be read control for the parallel slave port, or analog input5.
RE1/$\overline{WR}$/AN6	9	10	26	I/O	ST/TTL(3)	RE1 can also be write control for the parallel slave port, or analog input6.
RE2/$\overline{CS}$/AN7	10	11	27	I/O	ST/TTL(3)	RE2 can also be select control for the parallel slave port, or analog input7.
VSS	12,31	13,34	6,29	P	—	Ground reference for logic and I/O pins.
VDD	11,32	12,35	7,28	P	—	Positive supply for logic and I/O pins.
NC	—	1,17,28, 40	12,13, 33,34		—	These pins are not internally connected. These pins should be left unconnected.

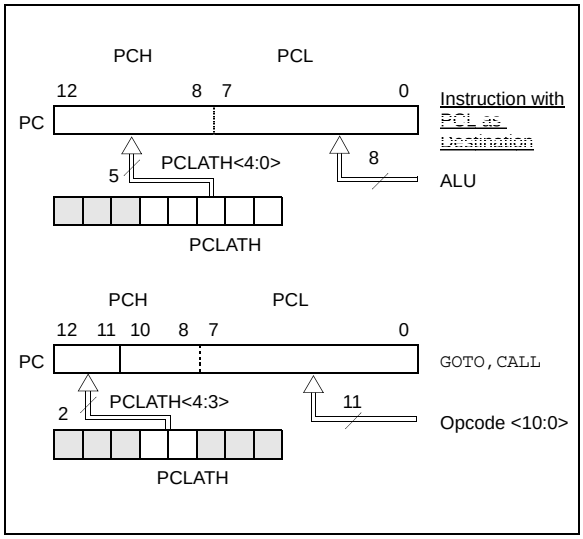
Legend: I = input O = output I/O = input/output P = power
— = Not used TTL = TTL input ST = Schmitt Trigger input

Note 1: This buffer is a Schmitt Trigger input when configured as an external interrupt.
2: This buffer is a Schmitt Trigger input when used in Serial Programming mode.
3: This buffer is a Schmitt Trigger input when configured as general purpose I/O and a TTL input when used in the Parallel Slave Port mode (for interfacing to a microprocessor bus).
4: This buffer is a Schmitt Trigger input when configured in RC oscillator mode and a CMOS input otherwise.

2.3 PCL and PCLATH

The program counter (PC) is 13-bits wide. The low byte comes from the PCL register, which is a readable and writable register. The upper bits (PC<12:8>) are not readable, but are indirectly writable through the PCLATH register. On any RESET, the upper bits of the PC will be cleared. Figure 2-5 shows the two situations for the loading of the PC. The upper example in the figure shows how the PC is loaded on a write to PCL (PCLATH<4:0> → PCH). The lower example in the figure shows how the PC is loaded during a CALL or GOTO instruction (PCLATH<4:3> → PCH).

FIGURE 2-5: LOADING OF PC IN DIFFERENT SITUATIONS



2.3.1 COMPUTED GOTO

A computed GOTO is accomplished by adding an offset to the program counter (ADDWF PCL). When doing a table read using a computed GOTO method, care should be exercised if the table location crosses a PCL memory boundary (each 256 byte block). Refer to the application note, *"Implementing a Table Read"* (AN556).

2.3.2 STACK

The PIC16F87X family has an 8-level deep x 13-bit wide hardware stack. The stack space is not part of either program or data space and the stack pointer is not readable or writable. The PC is PUSHed onto the stack when a CALL instruction is executed, or an interrupt causes a branch. The stack is POPed in the event of a RETURN, RETLW or a RETFIE instruction execution. PCLATH is not affected by a PUSH or POP operation.

The stack operates as a circular buffer. This means that after the stack has been PUSHed eight times, the ninth push overwrites the value that was stored from the first push. The tenth push overwrites the second push (and so on).

Note 1: There are no status bits to indicate stack overflow or stack underflow conditions.

2: There are no instructions/mnemonics called PUSH or POP. These are actions that occur from the execution of the CALL, RETURN, RETLW and RETFIE instructions, or the vectoring to an interrupt address.

2.4 Program Memory Paging

All PIC16F87X devices are capable of addressing a continuous 8K word block of program memory. The CALL and GOTO instructions provide only 11 bits of address to allow branching within any 2K program memory page. When doing a CALL or GOTO instruction, the upper 2 bits of the address are provided by PCLATH<4:3>. When doing a CALL or GOTO instruction, the user must ensure that the page select bits are programmed so that the desired program memory page is addressed. If a return from a CALL instruction (or interrupt) is executed, the entire 13-bit PC is popped off the stack. Therefore, manipulation of the PCLATH<4:3> bits is not required for the return instructions (which POPs the address from the stack).

Note: The contents of the PCLATH register are unchanged after a RETURN or RETFIE instruction is executed. The user must rewrite the contents of the PCLATH register for any subsequent subroutine calls or GOTO instructions.

Example 2-1 shows the calling of a subroutine in page 1 of the program memory. This example assumes that PCLATH is saved and restored by the Interrupt Service Routine (if interrupts are used).

EXAMPLE 2-1: CALL OF A SUBROUTINE IN PAGE 1 FROM PAGE 0

```
        ORG 0x500
        BCF PCLATH,4
        BSF PCLATH,3    ;Select page 1
                        ;(800h-FFFh)
        CALL SUB1_P1    ;Call subroutine in
        :               ;page 1 (800h-FFFh)
        :
        ORG 0x900       ;page 1 (800h-FFFh)
SUB1_P1
        :               ;called subroutine
                        ;page 1 (800h-FFFh)
        :
        RETURN          ;return to
                        ;Call subroutine
                        ;in page 0
                        ;(000h-7FFh)
```

3.5 PORTE and TRISE Register

PORTE and TRISE are not implemented on the PIC16F873 or PIC16F876.

PORTE has three pins (RE0/$\overline{RD}$/AN5, RE1/$\overline{WR}$/AN6, and RE2/$\overline{CS}$/AN7) which are individually configureable as inputs or outputs. These pins have Schmitt Trigger input buffers.

The PORTE pins become the I/O control inputs for the microprocessor port when bit PSPMODE (TRISE<4>) is set. In this mode, the user must make certain that the TRISE<2:0> bits are set, and that the pins are configured as digital inputs. Also ensure that ADCON1 is configured for digital I/O. In this mode, the input buffers are TTL.

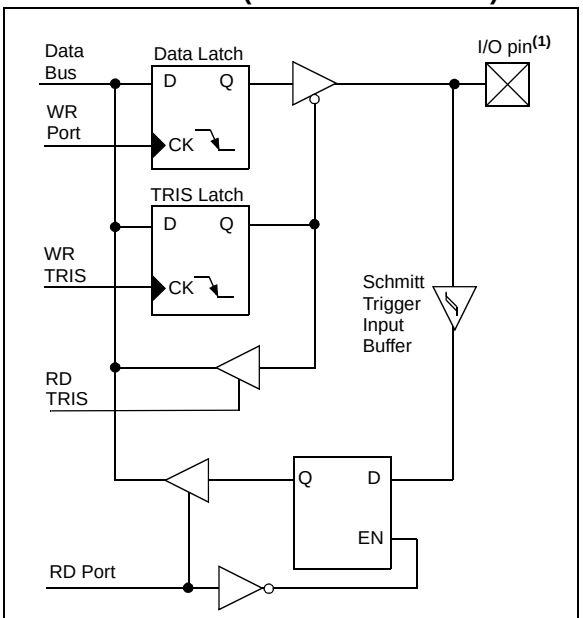
Register 3-1 shows the TRISE register, which also controls the parallel slave port operation.

PORTE pins are multiplexed with analog inputs. When selected for analog input, these pins will read as '0's.

TRISE controls the direction of the RE pins, even when they are being used as analog inputs. The user must make sure to keep the pins configured as inputs when using them as analog inputs.

Note:	On a Power-on Reset, these pins are configured as analog inputs, and read as '0'.

FIGURE 3-8: PORTE BLOCK DIAGRAM (IN I/O PORT MODE)



Note 1: I/O pins have protection diodes to VDD and VSS.

TABLE 3-9: PORTE FUNCTIONS

Name	Bit#	Buffer Type	Function
RE0/$\overline{RD}$/AN5	bit0	ST/TTL(1)	I/O port pin or read control input in Parallel Slave Port mode or analog input: $\overline{RD}$ 1 = Idle 0 = Read operation. Contents of PORTD register are output to PORTD I/O pins (if chip selected)
RE1/$\overline{WR}$/AN6	bit1	ST/TTL(1)	I/O port pin or write control input in Parallel Slave Port mode or analog input: $\overline{WR}$ 1 = Idle 0 = Write operation. Value of PORTD I/O pins is latched into PORTD register (if chip selected)
RE2/$\overline{CS}$/AN7	bit2	ST/TTL(1)	I/O port pin or chip select control input in Parallel Slave Port mode or analog input: $\overline{CS}$ 1 = Device is not selected 0 = Device is selected

Legend: ST = Schmitt Trigger input, TTL = TTL input
Note 1: Input buffers are Schmitt Triggers when in I/O mode and TTL buffers when in Parallel Slave Port mode.

TABLE 3-10: SUMMARY OF REGISTERS ASSOCIATED WITH PORTE

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other RESETS
09h	PORTE	—	—	—	—	—	RE2	RE1	RE0	---- -xxx	---- -uuu
89h	TRISE	IBF	OBF	IBOV	PSPMODE	—	PORTE Data Direction Bits			0000 -111	0000 -111
9Fh	ADCON1	ADFM	—	—	—	PCFG3	PCFG2	PCFG1	PCFG0	--0- 0000	--0- 0000

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are not used by PORTE.

4.9 FLASH Program Memory Write Protection

The configuration word contains a bit that write protects the FLASH program memory, called WRT. This bit can only be accessed when programming the PIC16F87X device via ICSP. Once write protection is enabled, only an erase of the entire device will disable it. When enabled, write protection prevents any writes to FLASH program memory. Write protection does not affect program memory reads.

TABLE 4-1: READ/WRITE STATE OF INTERNAL FLASH PROGRAM MEMORY

Configuration Bits			Memory Location	Internal Read	Internal Write	ICSP Read	ICSP Write
CP1	CP0	WRT					
0	0	x	All program memory	Yes	No	No	No
0	1	0	Unprotected areas	Yes	No	Yes	No
0	1	0	Protected areas	Yes	No	No	No
0	1	1	Unprotected areas	Yes	Yes	Yes	No
0	1	1	Protected areas	Yes	No	No	No
1	0	0	Unprotected areas	Yes	No	Yes	No
1	0	0	Protected areas	Yes	No	No	No
1	0	1	Unprotected areas	Yes	Yes	Yes	No
1	0	1	Protected areas	Yes	No	No	No
1	1	0	All program memory	Yes	No	Yes	Yes
1	1	1	All program memory	Yes	Yes	Yes	Yes

TABLE 4-2: REGISTERS ASSOCIATED WITH DATA EEPROM/PROGRAM FLASH

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other RESETS
0Bh, 8Bh, 10Bh, 18Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
10Dh	EEADR	EEPROM Address Register, Low Byte								xxxx xxxx	uuuu uuuu
10Fh	EEADRH	—	—	—	EEPROM Address, High Byte					xxxx xxxx	uuuu uuuu
10Ch	EEDATA	EEPROM Data Register, Low Byte								xxxx xxxx	uuuu uuuu
10Eh	EEDATH	—	—	EEPROM Data Register, High Byte						xxxx xxxx	uuuu uuuu
18Ch	EECON1	EEPGD	—	—	—	WRERR	WREN	WR	RD	x--- x000	x--- u000
18Dh	EECON2	EEPROM Control Register2 (not a physical register)								—	—
8Dh	PIE2	—	**(1)**	—	EEIE	BCLIE	—	—	CCP2IE	-r-0 0--0	-r-0 0--0
0Dh	PIR2	—	**(1)**	—	EEIF	BCLIF	—	—	CCP2IF	-r-0 0--0	-r-0 0--0

Legend: x = unknown, u = unchanged, r = reserved, - = unimplemented, read as '0'.
Shaded cells are not used during FLASH/EEPROM access.

Note 1: These bits are reserved; always maintain these bits clear.

TABLE 9-1: REGISTERS ASSOCIATED WITH SPI OPERATION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on: $\overline{MCLR}$, WDT
0Bh, 8Bh, 10Bh,18Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	PSPIF(1)	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
8Ch	PIE1	PSPIE(1)	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
13h	SSPBUF	Synchronous Serial Port Receive Buffer/Transmit Register								xxxx xxxx	uuuu uuuu
14h	SSPCON	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	0000 0000	0000 0000
94h	SSPSTAT	SMP	CKE	D/$\overline{A}$	P	S	R/$\overline{W}$	UA	BF	0000 0000	0000 0000

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are not used by the SSP in SPI mode.

Note 1: These bits are reserved on PCI16F873/876 devices; always maintain these bits clear.

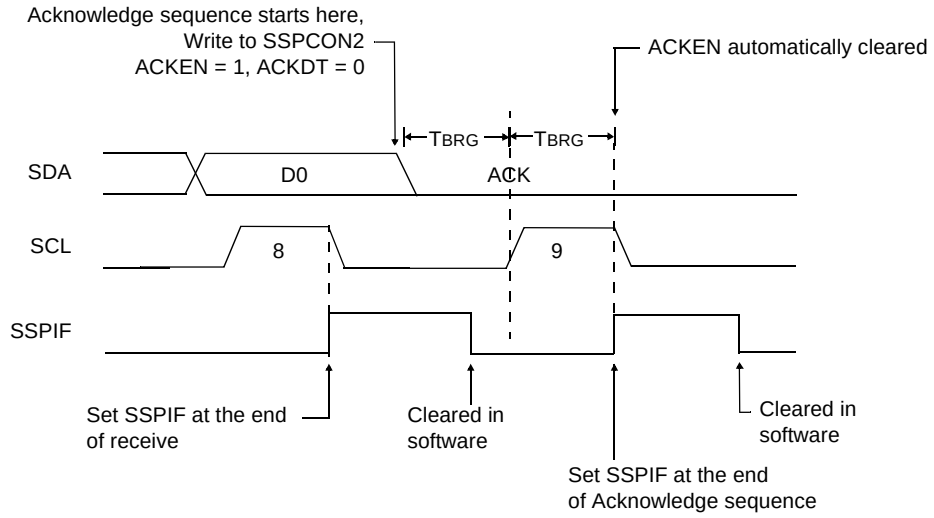
9.2.13 ACKNOWLEDGE SEQUENCE TIMING

An Acknowledge sequence is enabled by setting the Acknowledge Sequence Enable bit, ACKEN (SSPCON2<4>). When this bit is set, the SCL pin is pulled low and the contents of the Acknowledge data bit is presented on the SDA pin. If the user wishes to generate an Acknowledge, the ACKDT bit should be cleared. If not, the user should set the ACKDT bit before starting an Acknowledge sequence. The baud rate generator then counts for one rollover period (TBRG), and the SCL pin is de-asserted high. When the SCL pin is sampled high (clock arbitration), the baud rate generator counts for TBRG. The SCL pin is then pulled low. Following this, the ACKEN bit is automatically cleared, the baud rate generator is turned off, and the SSP module then goes into IDLE mode (Figure 9-16).

9.2.13.1 WCOL Status Flag

If the user writes the SSPBUF when an Acknowledge sequence is in progress, the WCOL is set and the contents of the buffer are unchanged (the write doesn't occur).

FIGURE 9-16: ACKNOWLEDGE SEQUENCE WAVEFORM



Note: TBRG = one baud rate generator period.

11.1 A/D Acquisition Requirements

For the A/D converter to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 11-2. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD), see Figure 11-2. **The maximum recommended impedance for analog sources is 10 kΩ.** As the impedance is decreased, the acquisition time may be decreased. After the analog input channel is selected (changed), this acquisition must be done before the conversion can be started.

To calculate the minimum acquisition time, Equation 11-1 may be used. This equation assumes that 1/2 LSb error is used (1024 steps for the A/D). The 1/2 LSb error is the maximum error allowed for the A/D to meet its specified resolution.

To calculate the minimum acquisition time, TACQ, see the PIC® MCU Mid-Range Reference Manual (DS33023).

EQUATION 11-1: ACQUISITION TIME

TACQ = Amplifier Settling Time + Hold Capacitor Charging Time + Temperature Coefficient

= TAMP + TC + TCOFF
= 2µs + TC + [(Temperature -25°C)(0.05µs/°C)]
TC = CHOLD (RIC + RSS + RS) In(1/2047)
= - 120pF (1kΩ + 7kΩ + 10kΩ) In(0.0004885)
= 16.47µs
TACQ = 2µs + 16.47µs + [(50°C -25°C)(0.05µs/°C)
= 19.72µs

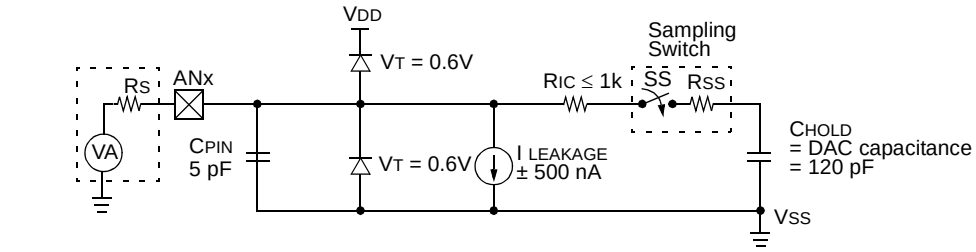
Note 1: The reference voltage (VREF) has no effect on the equation, since it cancels itself out.

2: The charge holding capacitor (CHOLD) is not discharged after each conversion.

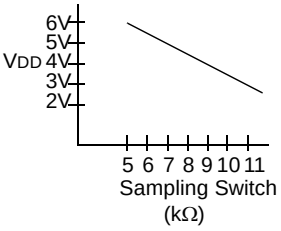
3: The maximum recommended impedance for analog sources is 10 kΩ. This is required to meet the pin leakage specification.

4: After a conversion has completed, a 2.0TAD delay must complete before acquisition can begin again. During this time, the holding capacitor is not connected to the selected A/D input channel.

FIGURE 11-2: ANALOG INPUT MODEL



Legend
CPIN = input capacitance
VT = threshold voltage
I LEAKAGE = leakage current at the pin due to various junctions
RIC = interconnect resistance
SS = sampling switch
CHOLD = sample/hold capacitance (from DAC)



11.5 A/D Operation During SLEEP

The A/D module can operate during SLEEP mode. This requires that the A/D clock source be set to RC (ADCS1:ADCS0 = 11). When the RC clock source is selected, the A/D module waits one instruction cycle before starting the conversion. This allows the SLEEP instruction to be executed, which eliminates all digital switching noise from the conversion. When the conversion is completed, the GO/DONE bit will be cleared and the result loaded into the ADRES register. If the A/D interrupt is enabled, the device will wake-up from SLEEP. If the A/D interrupt is not enabled, the A/D module will then be turned off, although the ADON bit will remain set.

When the A/D clock source is another clock option (not RC), a SLEEP instruction will cause the present conversion to be aborted and the A/D module to be turned off, though the ADON bit will remain set.

Turning off the A/D places the A/D module in its lowest current consumption state.

Note:	For the A/D module to operate in SLEEP, the A/D clock source must be set to RC (ADCS1:ADCS0 = 11). To allow the conversion to occur during SLEEP, ensure the SLEEP instruction immediately follows the instruction that sets the GO/DONE bit.

11.6 Effects of a RESET

A device RESET forces all registers to their RESET state. This forces the A/D module to be turned off, and any conversion is aborted. All A/D input pins are configured as analog inputs.

The value that is in the ADRESH:ADRESL registers is not modified for a Power-on Reset. The ADRESH:ADRESL registers will contain unknown data after a Power-on Reset.

TABLE 11-2: REGISTERS/BITS ASSOCIATED WITH A/D

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on MCLR, WDT
0Bh,8Bh, 10Bh,18Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	PSPIF(1)	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
8Ch	PIE1	PSPIE(1)	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
1Eh	ADRESH	A/D Result Register High Byte								xxxx xxxx	uuuu uuuu
9Eh	ADRESL	A/D Result Register Low Byte								xxxx xxxx	uuuu uuuu
1Fh	ADCON0	ADCS1	ADCS0	CHS2	CHS1	CHS0	GO/DONE	—	ADON	0000 00-0	0000 00-0
9Fh	ADCON1	ADFM	—	—	—	PCFG3	PCFG2	PCFG1	PCFG0	--0- 0000	--0- 0000
85h	TRISA	—	—	PORTA Data Direction Register						--11 1111	--11 1111
05h	PORTA	—	—	PORTA Data Latch when written: PORTA pins when read						--0x 0000	--0u 0000
89h(1)	TRISE	IBF	OBF	IBOV	PSPMODE	—	PORTE Data Direction bits			0000 -111	0000 -111
09h(1)	PORTE	—	—	—	—	—	RE2	RE1	RE0	---- -xxx	---- -uuu

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are not used for A/D conversion.

Note 1: These registers/bits are not available on the 28-pin devices.

12.4 Power-On Reset (POR)

A Power-on Reset pulse is generated on-chip when VDD rise is detected (in the range of 1.2V - 1.7V). To take advantage of the POR, tie the MCLR pin directly (or through a resistor) to VDD. This will eliminate external RC components usually needed to create a Power-on Reset. A maximum rise time for VDD is specified. See Electrical Specifications for details.

When the device starts normal operation (exits the RESET condition), device operating parameters (voltage, frequency, temperature,...) must be met to ensure operation. If these conditions are not met, the device must be held in RESET until the operating conditions are met. Brown-out Reset may be used to meet the start-up conditions. For additional information, refer to Application Note, AN007, “Power-up Trouble Shooting”, (DS00007).

12.5 Power-up Timer (PWRT)

The Power-up Timer provides a fixed 72 ms nominal time-out on power-up only from the POR. The Power-up Timer operates on an internal RC oscillator. The chip is kept in RESET as long as the PWRT is active. The PWRT’s time delay allows VDD to rise to an acceptable level. A configuration bit is provided to enable/disable the PWRT.

The power-up time delay will vary from chip to chip due to VDD, temperature and process variation. See DC parameters for details (TPWRT, parameter #33).

12.6 Oscillator Start-up Timer (OST)

The Oscillator Start-up Timer (OST) provides a delay of 1024 oscillator cycles (from OSC1 input) after the PWRT delay is over (if PWRT is enabled). This helps to ensure that the crystal oscillator or resonator has started and stabilized.

The OST time-out is invoked only for XT, LP and HS modes and only on Power-on Reset or Wake-up from SLEEP.

12.7 Brown-out Reset (BOR)

The configuration bit, BODEN, can enable or disable the Brown-out Reset circuit. If VDD falls below VBOR (parameter D005, about 4V) for longer than TBOR (parameter #35, about 100μS), the brown-out situation will reset the device. If VDD falls below VBOR for less than TBOR, a RESET may not occur.

Once the brown-out occurs, the device will remain in Brown-out Reset until VDD rises above VBOR. The Power-up Timer then keeps the device in RESET for TPWRT (parameter #33, about 72mS). If VDD should fall below VBOR during TPWRT, the Brown-out Reset process will restart when VDD rises above VBOR with the Power-up Timer Reset. The Power-up Timer is always enabled when the Brown-out Reset circuit is enabled, regardless of the state of the PWRT configuration bit.

12.8 Time-out Sequence

On power-up, the time-out sequence is as follows: The PWRT delay starts (if enabled) when a POR Reset occurs. Then OST starts counting 1024 oscillator cycles when PWRT ends (LP, XT, HS). When the OST ends, the device comes out of RESET.

If MCLR is kept low long enough, the time-outs will expire. Bringing MCLR high will begin execution immediately. This is useful for testing purposes or to synchronize more than one PIC16F87X device operating in parallel.

Table 12-5 shows the RESET conditions for the STATUS, PCON and PC registers, while Table 12-6 shows the RESET conditions for all the registers.

12.9 Power Control/Status Register (PCON)

The Power Control/Status Register, PCON, has up to two bits depending upon the device.

Bit0 is Brown-out Reset Status bit, BOR. Bit BOR is unknown on a Power-on Reset. It must then be set by the user and checked on subsequent RESETS to see if bit BOR cleared, indicating a BOR occurred. When the Brown-out Reset is disabled, the state of the BOR bit is unpredictable and is, therefore, not valid at any time.

Bit1 is POR (Power-on Reset Status bit). It is cleared on a Power-on Reset and unaffected otherwise. The user must set this bit following a Power-on Reset.

TABLE 12-3: TIME-OUT IN VARIOUS SITUATIONS

Oscillator Configuration	Power-up		Brown-out	Wake-up from SLEEP
	PWRTE = 0	PWRTE = 1		
XT, HS, LP	72 ms + 1024TOSC	1024TOSC	72 ms + 1024TOSC	1024TOSC
RC	72 ms	—	72 ms	—

TABLE 12-6: INITIALIZATION CONDITIONS FOR ALL REGISTERS

Register	Devices				Power-on Reset, Brown-out Reset	$\overline{\text{MCLR}}$ Resets, WDT Reset	Wake-up via WDT or Interrupt
W	873	874	876	877	xxxx xxxx	uuuu uuuu	uuuu uuuu
INDF	873	874	876	877	N/A	N/A	N/A
TMR0	873	874	876	877	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCL	873	874	876	877	0000h	0000h	PC + 1(2)
STATUS	873	874	876	877	0001 1xxx	000q quuu(3)	uuuq quuu(3)
FSR	873	874	876	877	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTA	873	874	876	877	--0x 0000	--0u 0000	--uu uuuu
PORTB	873	874	876	877	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTC	873	874	876	877	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTD	873	874	876	877	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTE	873	874	876	877	---- -xxx	---- -uuu	---- -uuu
PCLATH	873	874	876	877	---0 0000	---0 0000	---u uuuu
INTCON	873	874	876	877	0000 000x	0000 000u	uuuu uuuu(1)
PIR1	873	874	876	877	r000 0000	r000 0000	ruuu uuuu(1)
	873	874	876	877	0000 0000	0000 0000	uuuu uuuu(1)
PIR2	873	874	876	877	-r-0 0--0	-r-0 0--0	-r-u u--u(1)
TMR1L	873	874	876	877	xxxx xxxx	uuuu uuuu	uuuu uuuu
TMR1H	873	874	876	877	xxxx xxxx	uuuu uuuu	uuuu uuuu
T1CON	873	874	876	877	--00 0000	--uu uuuu	--uu uuuu
TMR2	873	874	876	877	0000 0000	0000 0000	uuuu uuuu
T2CON	873	874	876	877	-000 0000	-000 0000	-uuu uuuu
SSPBUF	873	874	876	877	xxxx xxxx	uuuu uuuu	uuuu uuuu
SSPCON	873	874	876	877	0000 0000	0000 0000	uuuu uuuu
CCPR1L	873	874	876	877	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCPR1H	873	874	876	877	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCP1CON	873	874	876	877	--00 0000	--00 0000	--uu uuuu
RCSTA	873	874	876	877	0000 000x	0000 000x	uuuu uuuu
TXREG	873	874	876	877	0000 0000	0000 0000	uuuu uuuu
RCREG	873	874	876	877	0000 0000	0000 0000	uuuu uuuu
CCPR2L	873	874	876	877	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCPR2H	873	874	876	877	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCP2CON	873	874	876	877	0000 0000	0000 0000	uuuu uuuu
ADRESH	873	874	876	877	xxxx xxxx	uuuu uuuu	uuuu uuuu
ADCON0	873	874	876	877	0000 00-0	0000 00-0	uuuu uu-u
OPTION_REG	873	874	876	877	1111 1111	1111 1111	uuuu uuuu
TRISA	873	874	876	877	--11 1111	--11 1111	--uu uuuu
TRISB	873	874	876	877	1111 1111	1111 1111	uuuu uuuu
TRISC	873	874	876	877	1111 1111	1111 1111	uuuu uuuu
TRISD	873	874	876	877	1111 1111	1111 1111	uuuu uuuu
TRISE	873	874	876	877	0000 -111	0000 -111	uuuu -uuu
PIE1	873	874	876	877	r000 0000	r000 0000	ruuu uuuu
	873	874	876	877	0000 0000	0000 0000	uuuu uuuu

Legend: u = unchanged, x = unknown, - = unimplemented bit, read as '0', q = value depends on condition, r = reserved, maintain clear

Note 1: One or more bits in INTCON, PIR1 and/or PIR2 will be affected (to cause wake-up).

2: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).

3: See Table 12-5 for RESET value for specific condition.

14.8 MPLAB ICD In-Circuit Debugger

Microchip's In-Circuit Debugger, MPLAB ICD, is a powerful, low cost, run-time development tool. This tool is based on the FLASH PIC16F87X and can be used to develop for this and other PIC microcontrollers from the PIC16CXXX family. The MPLAB ICD utilizes the in-circuit debugging capability built into the PIC16F87X. This feature, along with Microchip's In-Circuit Serial Programming™ protocol, offers cost-effective in-circuit FLASH debugging from the graphical user interface of the MPLAB Integrated Development Environment. This enables a designer to develop and debug source code by watching variables, single-stepping and setting break points. Running at full speed enables testing hardware in real-time.

14.9 PRO MATE II Universal Device Programmer

The PRO MATE II universal device programmer is a full-featured programmer, capable of operating in stand-alone mode, as well as PC-hosted mode. The PRO MATE II device programmer is CE compliant.

The PRO MATE II device programmer has programmable V_{DD} and V_{PP} supplies, which allow it to verify programmed memory at V_{DD} min and V_{DD} max for maximum reliability. It has an LCD display for instructions and error messages, keys to enter commands and a modular detachable socket assembly to support various package types. In stand-alone mode, the PRO MATE II device programmer can read, verify, or program PIC devices. It can also set code protection in this mode.

14.10 PICSTART Plus Entry Level Development Programmer

The PICSTART Plus development programmer is an easy-to-use, low cost, prototype programmer. It connects to the PC via a COM (RS-232) port. MPLAB Integrated Development Environment software makes using the programmer simple and efficient.

The PICSTART Plus development programmer supports all PIC devices with up to 40 pins. Larger pin count devices, such as the PIC16C92X and PIC17C76X, may be supported with an adapter socket. The PICSTART Plus development programmer is CE compliant.

14.11 PICDEM 1 Low Cost PIC MCU Demonstration Board

The PICDEM 1 demonstration board is a simple board which demonstrates the capabilities of several of Microchip's microcontrollers. The microcontrollers supported are: PIC16C5X (PIC16C54 to PIC16C58A), PIC16C61, PIC16C62X, PIC16C71, PIC16C8X, PIC17C42, PIC17C43 and PIC17C44. All necessary hardware and software is included to run basic demo programs. The user can program the sample microcontrollers provided with the PICDEM 1 demonstration board on a PRO MATE II device programmer, or a PICSTART Plus development programmer, and easily test firmware. The user can also connect the PICDEM 1 demonstration board to the MPLAB ICE in-circuit emulator and download the firmware to the emulator for testing. A prototype area is available for the user to build some additional hardware and connect it to the microcontroller socket(s). Some of the features include an RS-232 interface, a potentiometer for simulated analog input, push button switches and eight LEDs connected to PORTB.

14.12 PICDEM 2 Low Cost PIC16CXX Demonstration Board

The PICDEM 2 demonstration board is a simple demonstration board that supports the PIC16C62, PIC16C64, PIC16C65, PIC16C73 and PIC16C74 microcontrollers. All the necessary hardware and software is included to run the basic demonstration programs. The user can program the sample microcontrollers provided with the PICDEM 2 demonstration board on a PRO MATE II device programmer, or a PICSTART Plus development programmer, and easily test firmware. The MPLAB ICE in-circuit emulator may also be used with the PICDEM 2 demonstration board to test firmware. A prototype area has been provided to the user for adding additional hardware and connecting it to the microcontroller socket(s). Some of the features include a RS-232 interface, push button switches, a potentiometer for simulated analog input, a serial EEPROM to demonstrate usage of the I^2C™ bus and separate headers for connection to an LCD module and a keypad.

16.0 DC AND AC CHARACTERISTICS GRAPHS AND TABLES

The graphs and tables provided in this section are for **design guidance** and are **not tested**.

In some graphs or tables, the data presented is **outside specified operating range** (i.e., outside specified VDD range). This is for **information only** and devices are ensured to operate properly only within the specified range.

The data presented in this section is a **statistical summary** of data collected on units from different lots over a period of time and matrix samples. 'Typical' represents the mean of the distribution at 25°C. 'max' or 'min' represents (mean + 3σ) or (mean - 3σ) respectively, where σ is standard deviation, over the whole temperature range.

FIGURE 16-1: TYPICAL IDD vs. FOSC OVER VDD (HS MODE)

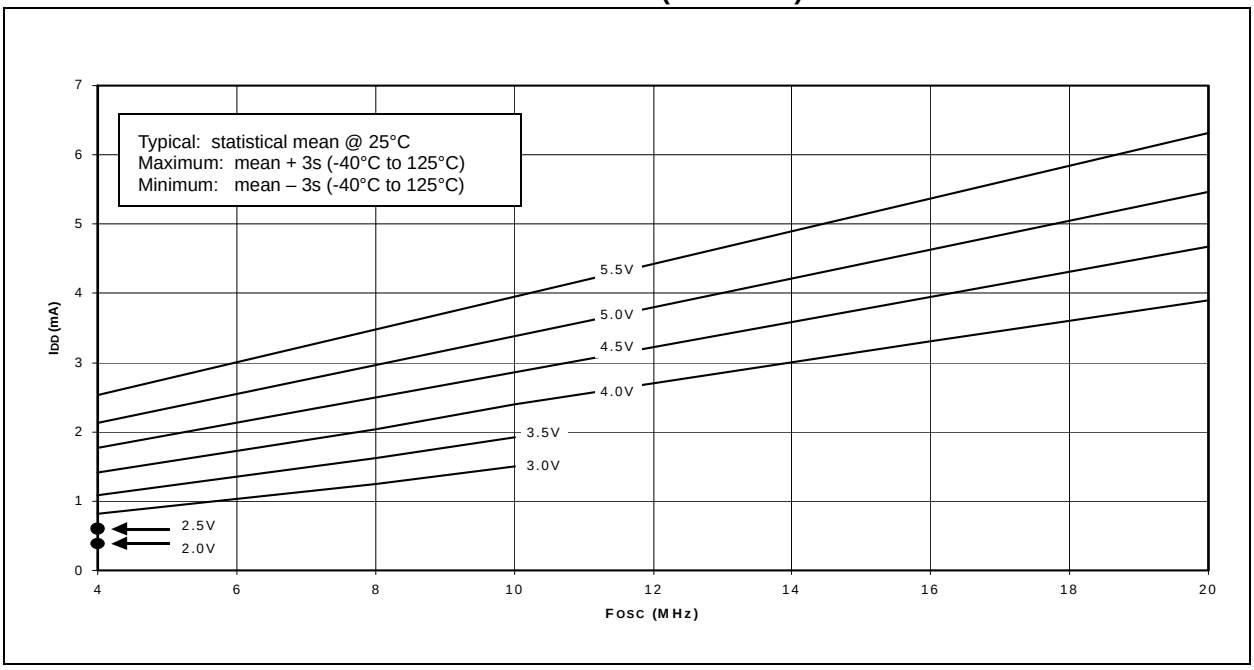


FIGURE 16-2: MAXIMUM IDD vs. FOSC OVER VDD (HS MODE)

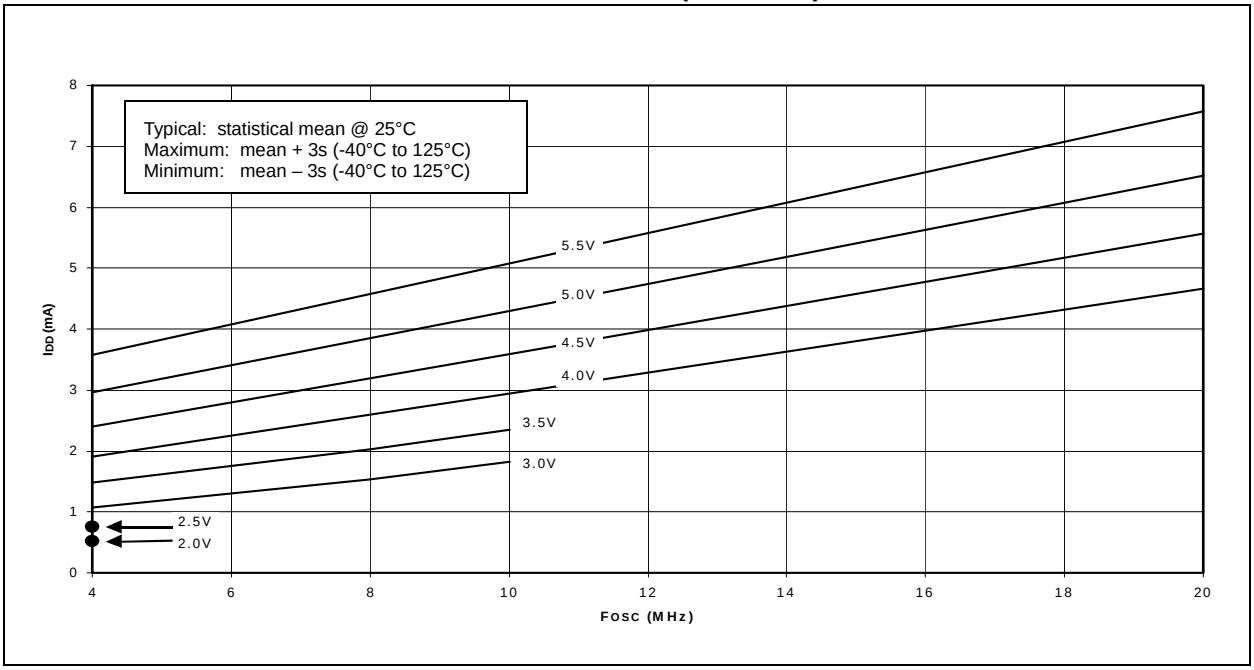


FIGURE 16-19: TYPICAL, MINIMUM AND MAXIMUM VOL vs. IOL (VDD=3V, -40°C TO 125°C)

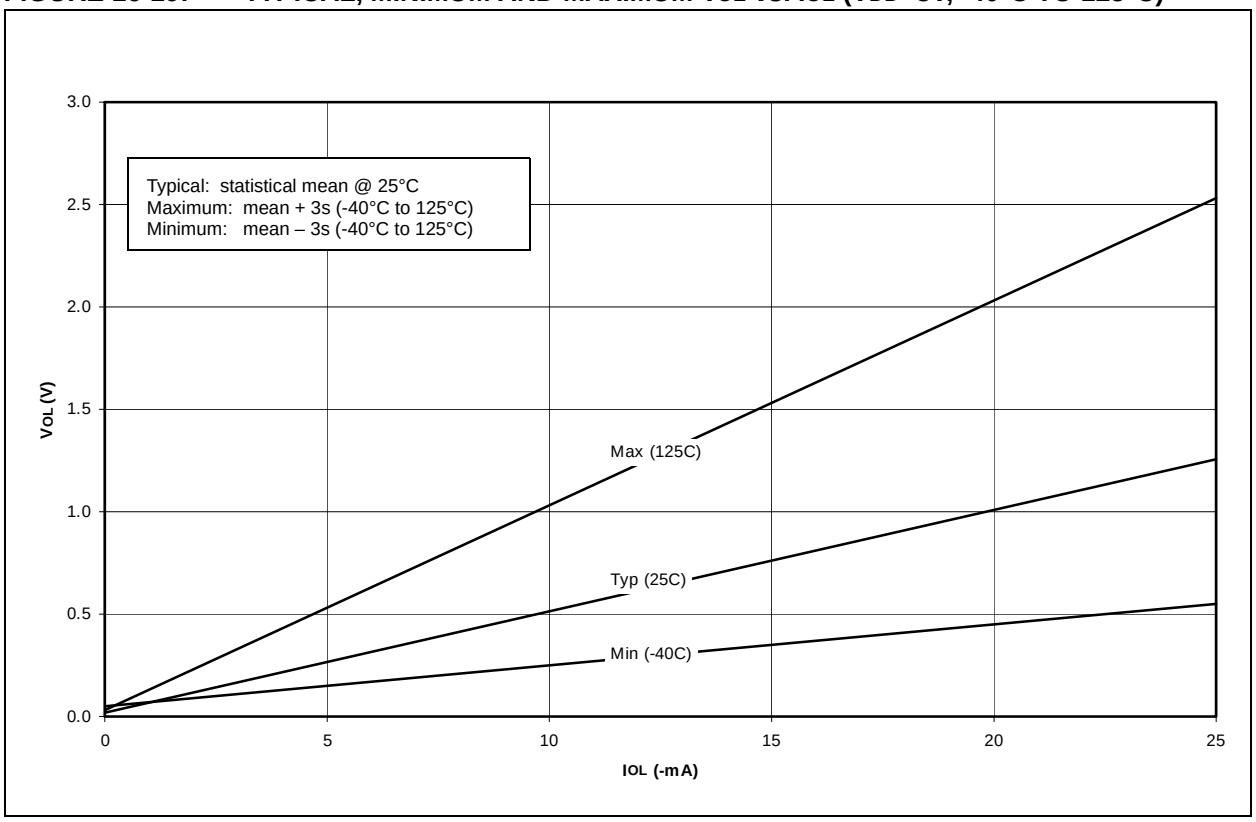
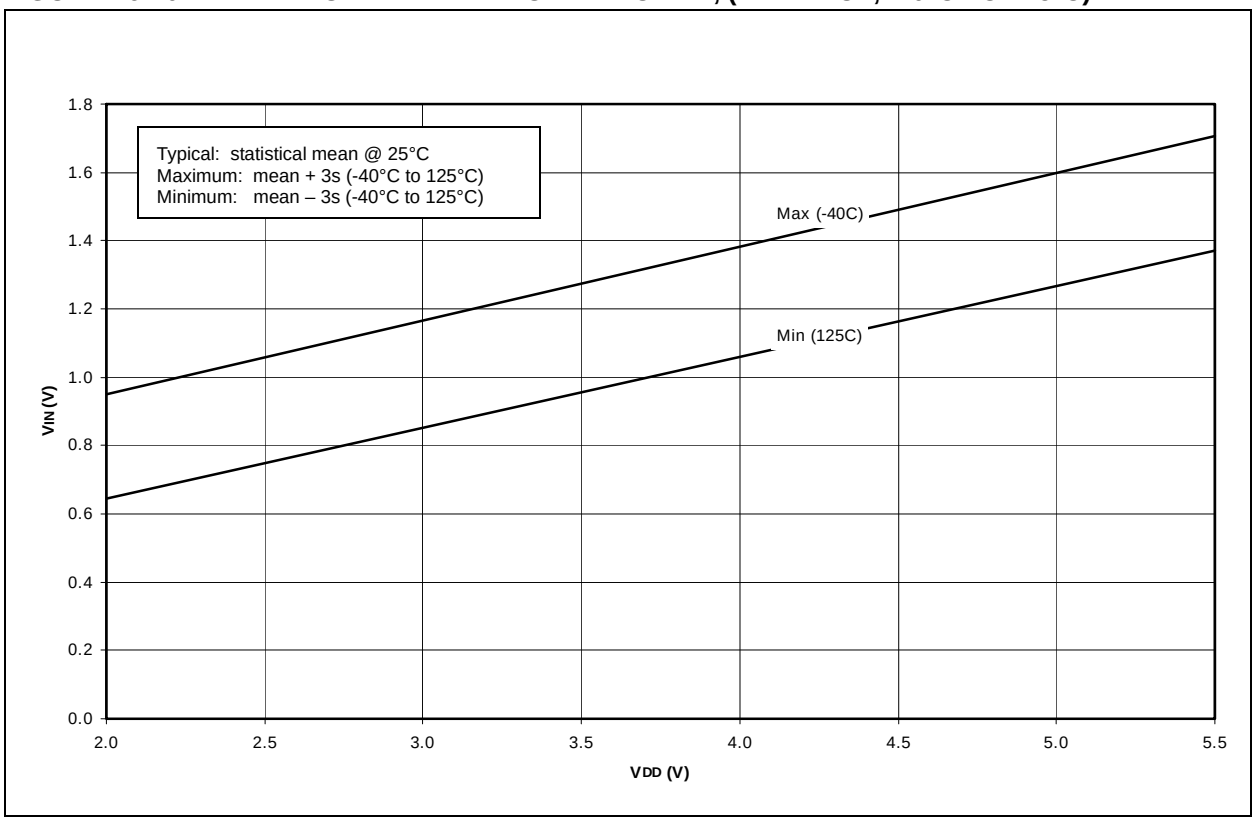


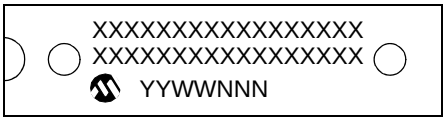
FIGURE 16-20: MINIMUM AND MAXIMUM VIN vs. VDD, (TTL INPUT, -40°C TO 125°C)



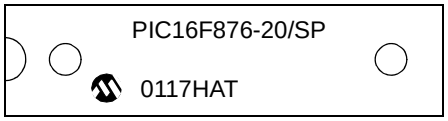
17.0 PACKAGING INFORMATION

17.1 Package Marking Information

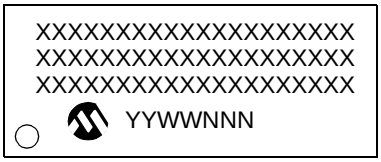
28-Lead PDIP (Skinny DIP)



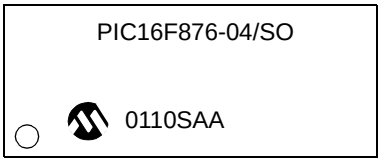
Example



28-Lead SOIC



Example

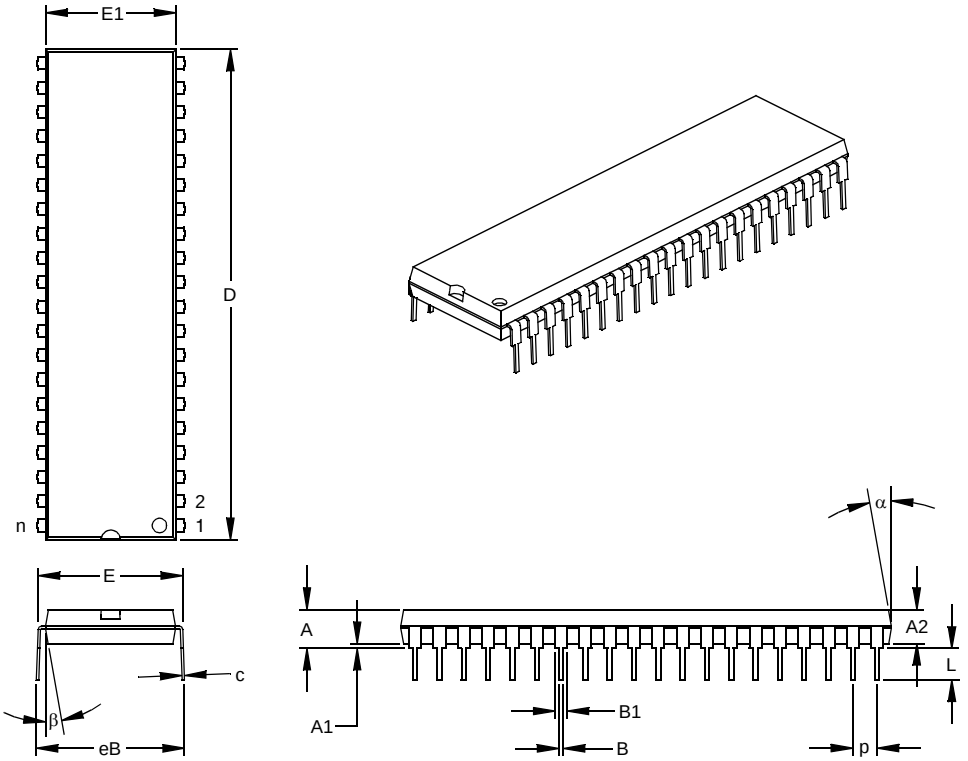


Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

40-Lead Plastic Dual In-line (P) – 600 mil (PDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



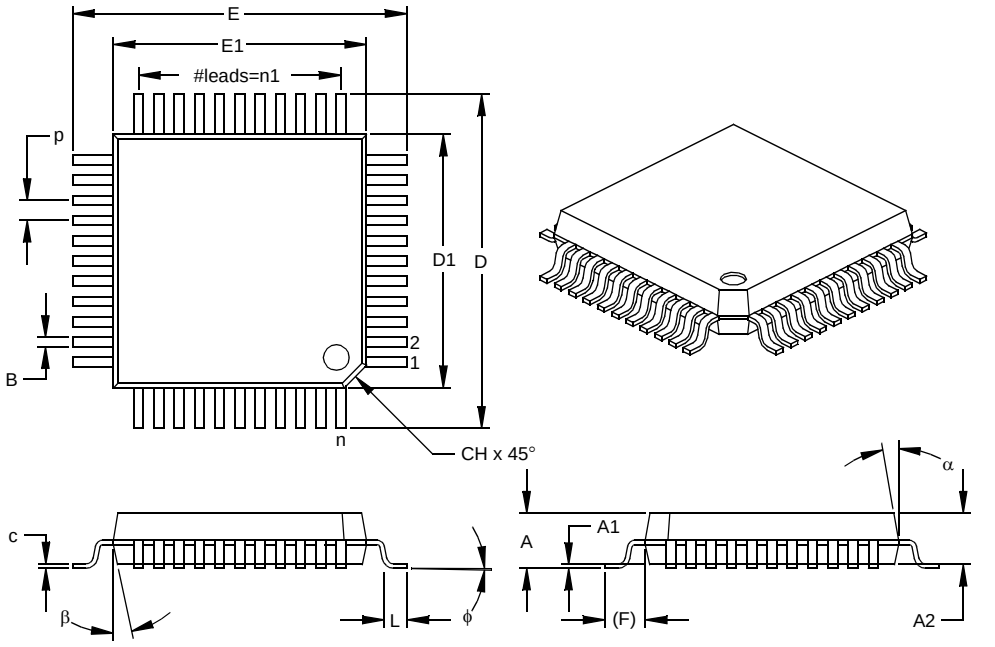
Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		40			40	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.160	.175	.190	4.06	4.45	4.83
Molded Package Thickness	A2	.140	.150	.160	3.56	3.81	4.06
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.595	.600	.625	15.11	15.24	15.88
Molded Package Width	E1	.530	.545	.560	13.46	13.84	14.22
Overall Length	D	2.045	2.058	2.065	51.94	52.26	52.45
Tip to Seating Plane	L	.120	.130	.135	3.05	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.030	.050	.070	0.76	1.27	1.78
Lower Lead Width	B	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing §	eB	.620	.650	.680	15.75	16.51	17.27
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MO-011
Drawing No. C04-016

44-Lead Plastic Metric Quad Flatpack (PQ) 10x10x2 mm Body, 1.6/0.15 mm Lead Form (MQFP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES			MILLIMETERS*		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		44			44	
Pitch	p		.031			0.80	
Pins per Side	n1		11			11	
Overall Height	A	.079	.086	.093	2.00	2.18	2.35
Molded Package Thickness	A2	.077	.080	.083	1.95	2.03	2.10
Standoff §	A1	.002	.006	.010	0.05	0.15	0.25
Foot Length	L	.029	.035	.041	0.73	0.88	1.03
Footprint (Reference)	(F)		.063			1.60	
Foot Angle	φ	0	3.5	7	0	3.5	7
Overall Width	E	.510	.520	.530	12.95	13.20	13.45
Overall Length	D	.510	.520	.530	12.95	13.20	13.45
Molded Package Width	E1	.390	.394	.398	9.90	10.00	10.10
Molded Package Length	D1	.390	.394	.398	9.90	10.00	10.10
Lead Thickness	c	.005	.007	.009	0.13	0.18	0.23
Lead Width	B	.012	.015	.018	0.30	0.38	0.45
Pin 1 Corner Chamfer	CH	.025	.035	.045	0.64	0.89	1.14
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MS-022
Drawing No. C04-071

O

P

NOTES: